



## **【OFC 2026】 Sigurd to Showcase Advanced Packaging and Testing Capabilities for AI, Silicon Photonics, and High-Speed Transmission Applications**

LOS ANGELES, CA — As generative AI, cloud computing, and data center infrastructure continue to advance rapidly, demand for high-speed interconnects, optical communications, silicon photonics, and advanced packaging is surging. Sigurd Microelectronics Corporation ( “Sigurd” ), a leading semiconductor packaging and testing service provider, announced that it will participate in OFC 2026 and exhibit at West Hall, Booth 4673, at the Los Angeles Convention Center. Through its participation, Sigurd aims to showcase its advanced capabilities and seize emerging opportunities driven by AI infrastructure, high-speed transmission, silicon photonics, and advanced testing applications.

OFC is one of the most influential annual events in the global optical communications and optical networking industry, bringing together key players across optical components, system equipment, data centers, and the semiconductor supply chain. With exhibition space for OFC 2026 reportedly sold out, the event underscores the rapid expansion of AI-driven network upgrades and bandwidth demand, while also serving as a key barometer for global trends in optical communications, silicon photonics, and data center technologies.

Sigurd noted that as AI servers, high-performance computing (HPC), and cloud data centers evolve toward higher bandwidth, lower latency, and greater energy efficiency, packaging and testing have become critical enablers of volume production and system reliability for next-generation semiconductors. At OFC 2026, Sigurd will focus on markets including AI, ASIC, HPC, networking, and silicon photonics, demonstrating its technological strengths and service excellence in advanced packaging and testing.

As AI data centers continue to expand and silicon photonics technologies gain momentum, market expectations for test accuracy, process stability, and manufacturing consistency are rising. In response, Sigurd has continued to invest in smart manufacturing, process automation, digitalized management, and advanced testing platforms. By integrating engineering expertise with advanced equipment and manufacturing capabilities, Sigurd has enhanced quality consistency, traceability, and production efficiency to meet the growing demand for advanced chips and high-speed communications components.

Participation in OFC serves not only as a platform for Sigurd to expand international partnerships, but also as an opportunity to stay aligned with next-generation trends in optoelectronic integration. Looking ahead, Sigurd will continue to focus on Advanced Test Technology, Automation, and AI Factory as its core development pillars, further strengthening its advanced packaging and testing integration capabilities to capture the next wave of semiconductor industry transformation alongside its global customers.

### **Exhibition Information**

**Exhibition Name:** OFC 2026

**Exhibition Dates:** March 17–19, 2026

**Technical Conference:** March 15–19, 2026

**Venue:** Los Angeles Convention Center, Los Angeles, California, USA

**Booth Number:** West Hall 4673

*invitation*

邀請函

**OFC** The Future of Optical Networking  
and Communications - Los Angeles, CA  
**March 17-19 (Tue-Thu), 2026**

展會時間 Exhibition Date

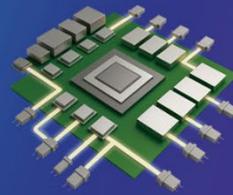
**2026年03月17日(週二)至19日(週四)**  
Mar 17-18 (Tue-Wed) | 10:00 – 17:00 (PT)  
Mar 19 (Thu) | 10:00 – 16:00 (PT)

展位號碼 Booth No.

**4673 (West Hall)**

展會地點 Exhibition Location

**美國加州洛杉磯會展中心**  
Los Angeles Convention Center  
Los Angeles, California, United States



矽格十年磨一劍，精研技術、打造封測系統與品質  
歡迎半導體先進舊雨新知，蒞臨指導

